12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250728000.1
Qualify New Assembly Material set for Selected Device(s)
Change Notification / Sample Request

Date: July 28, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250728000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC25630-2DDBR	UCC25630-2DDBR
UCC256402DDBT	NULL
UCC256404DDBT	NULL
UCC256402DDBR	NULL
UCC25630-2DDBT	UCC25630-2DDBT
UCC25630-3DDBT	UCC25630-3DDBT
UCC256404DDBR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250728000.1	**PCN Date:**	July 28, 2025
Title:	Qualify New Assembly Material set for Selected Device(s)		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	October 26, 2025	**Sample requests accepted until:**	September 26, 2025

***Sample requests received after** September 26, 2025 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

	Current	Proposed
Wire diam/type	1.0mil Au	1.0mil Cu
Mount compound	4042500	4147858
Mold compound	4212090	4221499
Top protective layer	N/A	Polyimide coat

Reason for Change:

Current mount compound will stop production September 2025 by the supplier.
Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

UCC25630-1DDBR	UCC256402ADDBR	UCC256403DDBT	UCC256404LDDBR
UCC25630-1DDBT	UCC256402ADDBT	UCC256403LDDBR	UCC256404LDDBT
UCC25630-2DDBR	UCC256402DDBR	UCC256403LDDBT	UCC25640DDBR
UCC25630-2DDBT	UCC256402DDBT	UCC256404ADDBR	UCC25640DDBT
UCC25630-3DDBR	UCC256402LDDBR	UCC256404ADDBT	UCC256501DDBR

UCC25630-3DDBT	UCC256402LDDBT	UCC256404BDDBR	UCC256501DDBT
UCC25630-4DDBR	UCC256403ADDBR	UCC256404DDBR	
UCC25630-4DDBT	UCC256403DDBR	UCC256404DDBT	

Qualification Data

Approve Date 17-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC25630-4DDBR	QBS Package/Process/Product Reference: UCC256604DDBR	QBS Reference: UCC256601DDBR	QBS Package Reference: ISO6741QDWQ1	QBS Process Reference: UCC27712QDRQ1	QBS Package Reference: UCC28730QDRQ1	QBS Package Reference: UCC28730DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	-	3/231/0	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	3/231/0	-	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	-	3/231/0	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	3/231/0	-	3/135/0	-	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	1/15/0	-
SD	C3	PB-Free Solderability	>95% Lead Coverage 8 Hr Steam Age	-	-	-	-	1/15/0	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	1/3/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device UCC25630-4DDBR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-090

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and

reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.